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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Data lla	
Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	EBI/EMI, I ² C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	88
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam7se32b-au



2. **Block Diagram**

TDI TDO TMS TCK ICE ARM7TDMI JTAG Processor **SCAN** JTAGSEL 1.8V VDDIN Voltage GND System Controller VDDOUT Regulato TST FIQ VDDCORE Memory Controller AIC VDDIO IRQ0-IRQ1 Embedded SRAM Address 32 Kbytes (SE512/256) or 8 Kbytes (SE32) Flash DBGU PDC DRXD DTXD Misalignmer PDC Status Detection PCK0-PCK2 VDDELASH Flash Memory Protection PLLRC 512 Kbytes (SE512) 256 Kbytes (SE256) 32 Kbytes (SE32) PLL Unit ERASE XIN osc PMC XOUT RCOSC Peripheral Bridge VDDFLASH BOD ROM VDDCORE Reset Peripheral DMA Controller POR Controller **VDDCORE PGMRDY** PGMNVALID PGMNOE PGMCK 11 Channels Fast Flash NRST Programming PGMCK PGMM0-PGMM3 PGMD0-PGMD15 PGMNCMD PGMEN0-PGMEN1 Interface PIT APB WDT SAM-BA RTT PIOC PIOA D[31:0]
A0/NBS0
A1/NBS2
A1/NBS2
A1/NBS2
A1/S21, A[20:18]
A21/NANDALE
A22/REG/NANDCLE
A16/BA0
A17/BA1
NCS0
NCS1/SDCS
NCS2/CFCS1
NCS2/MANDCS
NRD/CFOE
NWR0/NWE/CFWR
NWB1/NBS1/CFION
NBS3/CFIOW
SDCKE
RAS PIOB FBI RXD0 TXD0 SCK0 RTS0 CTS0 RXD1 TXD1 SCK1 RTS1 DCD1 DSR1 DTR1 RI1 PDC USART0 CompactFlash PDC NAND Flash PDC USART1 SDRAM Controller SDCRE
RAS
CAS
SDWE
SDA10
CFRNW
NCS4/CFCS0
NCS5/CFCE1
NCS6/CFCE2
NCS7
NANDOWE PDC RI1 NPCS0 NPCS1 NPCS2 NPCS3 MISO MOSI SPCK PDC SPI Static Memory Controller NANDWE NWAIT TCLK0 TCLK1 TCLK2 Timer Counter ECC SDCK Controller TIOA0 TC0 TIOA0 TIOA1 TIOA1 TIOA2 TIOA2 TC1 FIFO **USB** Device TC2 ADTRG AD0 AD1 AD2 AD3 AD4 AD5 AD6 AD7 PDC PWM0 PWM1 PWM2 PWM3 TF TK TD RD RK RF **PWMC** ADC SSC PDC ADVREF TWD TWCK TWI

Figure 2-1. SAM7SE512/256/32 Block Diagram Signal Description

SAM7SE512/256/32 Summary

 Table 3-1.
 Signal Description List (Continued)

Signal Name	Function	Туре	Active Level	Comments			
Two-Wire Interface							
TWD	Two-wire Serial Data	I/O					
TWCK	Two-wire Serial Clock	I/O					
	Analog-to-Dig	ital Converter					
AD0-AD3	Analog Inputs	Analog		Digital pulled-up inputs at reset			
AD4-AD7	Analog Inputs	Analog		Analog Inputs			
ADTRG	ADC Trigger	Input					
ADVREF	ADC Reference	Analog					
	Fast Flash Progra	amming Interfa	се				
PGMEN0-PGMEN2	Programming Enabling	Input					
PGMM0-PGMM3	Programming Mode	Input					
PGMD0-PGMD15	Programming Data	I/O					
PGMRDY	Programming Ready	Output	High				
PGMNVALID	Data Direction	Output	Low				
PGMNOE	Programming Read	Input	Low				
PGMCK	Programming Clock	Input					
PGMNCMD	Programming Command	Input	Low				
	External Bu	ıs Interface	I.				
D[31:0]	Data Bus	I/O					
A[22:0]	Address Bus	Output					
NWAIT	External Wait Signal	Input	Low				
	Static Memo	ry Controller					
NCS[7:0]	Chip Select Lines	Output	Low				
NWR[1:0]	Write Signals	Output	Low				
NRD	Read Signal	Output	Low				
NWE	Write Enable	Output	Low				
NUB	NUB: Upper Byte Select	Output	Low				
NLB	NLB: Lower Byte Select	Output	Low				
EBI for CompactFlash Support							
CFCE[2:1]	CompactFlash Chip Enable	Output	Low				
CFOE	CompactFlash Output Enable	Output	Low				
CFWE	CompactFlash Write Enable	Output	Low				
CFIOR	CompactFlash I/O Read Signal	Output	Low				
CFIOW	CompactFlash I/O Write Signal	Output	Low				
CFRNW	CompactFlash Read Not Write Signal	Output					
CFCS[1:0]	CompactFlash Chip Select Lines	Output	Low				





4.2 128-lead LQFP Pinout

 Table 4-1.
 Pinout in 128-lead LQFP Package

1	ADVREF		
2	GND		
3	AD7		
4	AD6		
5	AD5		
6	AD4		
7	VDDOUT		
8	VDDIN		
9	PA20/PGMD8/AD3		
10	PA19/PGMD7/AD2		
11	PA18/PGMD6/AD1		
12	PA17/PGMD5/AD0		
13	PA16/PGMD4		
14	PA15/PGMD3		
15	PA14/PGMD2		
16	PA13/PGMD1		
17	PA12/PGMD0		
18	PA11/PGMM3		
19	PA10/PGMM2		
20	PA9/PGMM1		
21	VDDIO		
22	GND		
23	VDDCORE		
24	PA8/PGMM0		
25	PA7/PGMNVALID		
26	PA6/PGMNOE		
27	PA5/PGMRDY		
28	PA4/PGMNCMD		
29	PA3		
30	PA2/PGMEN2		
31	PA1/PGMEN1		
32	PA0/PGMEN0		

	3 -			
33	PB31			
34	PB30			
35	PB29			
36	PB28			
37	PB27			
38	PB26			
39	PB25			
40	PB24			
41	PB23			
42	PB22			
43	PB21			
44	PB20			
45	GND			
46	VDDIO			
47	VDDCORE			
48	PB19			
49	PB18			
50	PB17			
51	PB16			
52	PB15			
53	PB14			
54	PB13			
55	PB12			
56	PB11			
57	PB10			
58	PB9			
59	PB8			
60	PB7			
61	PB6			
62	PB5			
63	PB4			
64	PB3			

65	TDI
66	TDO
67	PB2
68	PB1
69	PB0
70	GND
71	VDDIO
72	VDDCORE
73	NRST
74	TST
75	ERASE
76	TCK
77	TMS
78	JTAGSEL
79	PC23
80	PC22
81	PC21
82	PC20
83	PC19
84	PC18
85	PC17
86	PC16
87	PC15
88	PC14
89	PC13
90	PC12
91	PC11
92	PC10
93	PC9
94	GND
95	VDDIO
96	VDDCORE
·	· · · · · · · · · · · · · · · · · · ·

97	SDCK		
98	PC8		
99	PC7		
100	PC6		
101	PC5		
102	PC4		
103	PC3		
104	PC2		
105	PC1		
106	PC0		
107	PA31		
108	PA30		
109	PA29		
110	PA28		
111	PA27/PGMD15		
112	PA26/PGMD14		
113	PA25/PGMD13		
114	PA24/PGMD12		
115	PA23/PGMD11		
116	PA22/PGMD10		
117	PA21/PGMD9		
118	VDDCORE		
119	GND		
120	VDDIO		
121	DM		
122	DP		
123	VDDFLASH		
124	GND		
125	XIN/PGMCK		
126	XOUT		
127	PLLRC		
128	VDDPLL		



4.4 144-ball LFBGA Pinout

Table 4-2. SAM7SE512/256/32 Pinout for 144-ball LFBGA Package

Table	4-2. SAIVI7 SEST2/2
Pin	Signal Name
A1	PB7
A2	PB8
A3	PB9
A4	PB12
A 5	PB13
A6	PB16
A7	PB22
A8	PB23
A9	PB25
A10	PB29
A11	PB30
A12	PB31
B1	PB6
B2	PB3
В3	PB4
B4	PB10
B5	PB14
В6	PB18
B7	PB20
B8	PB24
В9	PB28
B10	PA4/PGMNCMD
B11	PA0/PGMEN0
B12	PA1/PGMEN1
C1	PB0
C2	PB1
СЗ	PB5
C4	PB11
C5	PB15
C6	PB19
C7	PB21
C8	PB27
C9	PA6/PGMNOE
C10	PA5/PGMRDY
C11	PA2/PGMEN2
C12	PA3

6/32 Pinout for 144-ball LF				
_	Signal Name			
D1	VDDCORE			
D2	VDDCORE			
D3	PB2			
D4	TDO			
D5	TDI			
D6	PB17			
D7	PB26			
D8	PA14/PGMD2			
D9	PA12/PGMD0			
D10	PA11/PGMM3			
D11	PA8/PGMM0			
D12	PA7/PGMNVALID			
E1	PC22			
E2	PC23			
E3	NRST			
E4	TCK			
E5	ERASE			
E6	TEST			
E7	VDDCORE			
E8	VDDCORE			
E9	GND			
E10	PA9/PGMM1			
E11	PA10/PGMM2			
E12	PA13/PGMD1			
F1	PC21			
F2	PC20			
F3	PC19			
F4	JTAGSEL			
F5	TMS			
F6	VDDIO			
F7	GND			
F8	GND			
F9	GND			
F10	AD5			
F11 PA15/PGMD3				
F12	2 PA16/PGMD4			

~	<u> Раскаде</u>				
	Pin	Pin Signal Name			
	G1	PC18			
	G2	PC16			
	G3	PC17			
	G4	PC9			
	G5	VDDIO			
	G6	GND			
	G7	GND			
	G8	GND			
	G9	GND			
	G10	AD4			
	G11	VDDIN			
	G12	VDDOUT			
	H1	PC15			
	H2	PC14			
	НЗ	PC13			
	H4	VDDCORE			
	H5	VDDCORE			
H6 GND H7 GND		GND			
		GND			
	H8	GND			
	H9	GND			
	H10	PA19/PGMD7/AD2			
	H11	PA20/PGMD8/AD3			
	H12	VDDIO			
	J1	PC12			
	J2	PC10			
	J3	PA30			
	J4	PA28			
	J5	PA23/PGMD11			
J6 PA22/PGMD10		PA22/PGMD10			
	J7 AD6				
	J8 AD7				
	J9 VDDCORE J10 VDDCORE J11 VDDCORE				
	J12	VDDIO			

Signal Name	
PC11	
PC6	
PC2	
PC0	
PA27/PGMD15	
PA26/PGMD14	
GND	
VDDCORE	
VDDFLASH	
VDDIO	
VDDIO	
PA18/PGMD6/AD1	
SDCK	
PC7	
PC4	
PC1	
PA29	
PA24/PGMD12	
PA21/PGMD9	
ADVREF	
VDDFLASH	
VDDFLASH	
PA17/PGMD5/AD0	
GND	
PC8	
PC5	
PC3	
PA31	
PA25/PGMD13	
DM	
DP	
GND	
XIN/PGMCK	
XOUT	
PLLRC	
VDDPLL	



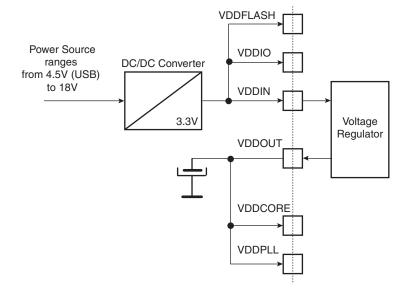
• One external 2.2 μF (or 3.3 μF) X7R capacitor should be connected between VDDOUT and GND.

Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. The input decoupling capacitor should be placed close to the chip. For example, two capacitors can be used in parallel: 100 nF NPO and 4.7 μ F X7R.

5.4 Typical Powering Schematics

The SAM7SE512/256/32 supports a 3.3V single supply mode. The internal regulator input connected to the 3.3V source and its output feeds VDDCORE and the VDDPLL. Figure 5-1 shows the power schematics to be used for USB bus-powered systems.

Figure 5-1. 3.3V System Single Power Supply Schematic





6.5 SDCK Pin

The SDCK pin is dedicated to the SDRAM Clock and is an output-only without pull-up. Maximum Output Frequency of this pad is 48 MHz at 3.0V and 25 MHz at 1.65V with a maximum load of 30 pF.

6.6 PIO Controller lines

All the I/O lines PA0 to PA31, PB0 to PB31, PC0 to PC23 integrate a programmable pull-up resistor. Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

Typical pull-up value is 100 k Ω

All the I/O lines have schmitt trigger inputs.

6.7 I/O Lines Current Drawing

The PIO lines PA0 to PA3 are high-drive current capable. Each of these I/O lines can drive up to 16 mA permanently.

The remaining I/O lines can draw only 8 mA.

However, the total current drawn by all the I/O lines cannot exceed 300 mA.

7. Processor and Architecture

7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
 - Runs at up to 55 MHz, providing 0.9 MIPS/MHz (core supplied with 1.8V)
- Two instruction sets
 - ARM® high-performance 32-bit instruction set
 - Thumb® high code density 16-bit instruction set
- Three-stage pipeline architecture
 - Instruction Fetch (F)
 - Instruction Decode (D)
 - Execute (E)

7.2 Debug and Test Features

- EmbeddedICE[™] (Integrated embedded in-circuit emulator)
 - Two watchpoint units
 - Test access port accessible through a JTAG protocol
 - Debug communication channel
- Debug Unit
 - Two-pin UART
 - Debug communication channel interrupt handling
 - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

7.3 Memory Controller

- Programmable Bus Arbiter
 - Handles requests from the ARM7TDMI and the Peripheral DMA Controller
- · Address decoder provides selection signals for
 - Four internal 1 Mbyte memory areas
 - One 256-Mbyte embedded peripheral area
 - Eight external 256-Mbyte memory areas
- Abort Status Registers
 - Source, Type and all parameters of the access leading to an abort are saved
 - Facilitates debug by detection of bad pointers
- Misalignment Detector
 - Alignment checking of all data accesses
 - Abort generation in case of misalignment
- Remap Command
 - Remaps the SRAM in place of the embedded non-volatile memory
 - Allows handling of dynamic exception vectors
- 16-area Memory Protection Unit (Internal Memory and peripheral protection only)



- Multiple device adaptability
 - Compliant with LCD Module
 - Compliant with PSRAM in synchronous operations
 - Programmable Setup Time Read/Write
 - Programmable Hold Time Read/Write
- Multiple Wait State Management
 - Programmable Wait State Generation
 - External Wait Request
 - Programmable Data Float Time

7.6 SDRAM Controller

- Numerous configurations supported
 - 2K, 4K, 8K Row Address Memory Parts
 - SDRAM with two or four Internal Banks
 - SDRAM with 16- or 32-bit Data Path
- · Programming facilities
 - Word, half-word, byte access
 - Automatic page break when Memory Boundary has been reached
 - Multibank Ping-pong Access
 - Timing parameters specified by software
 - Automatic refresh operation, refresh rate is programmable
- Energy-saving capabilities
 - Self-refresh, and Low-power Modes supported
- Error detection
 - Refresh Error Interrupt
- SDRAM Power-up Initialization by software
- Latency is set to two clocks (CAS Latency of 1, 3 Not Supported)
- Auto Precharge Command not used
- Mobile SDRAM supported (except for low-power extended mode and deep power-down mode)

7.7 Error Corrected Code Controller

- Tracking the accesses to a NAND Flash device by triggering on the corresponding chip select
- Single bit error correction and 2-bit Random detection.
- Automatic Hamming Code Calculation while writing
 - ECC value available in a register
- Automatic Hamming Code Calculation while reading
 - Error Report, including error flag, correctable error flag and word address being detected erroneous
 - Supports 8- or 16-bit NAND Flash devices with 512-, 1024-, 2048- or 4096-byte pages





7.8 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Eleven channels
 - Two for each USART
 - Two for the Debug Unit
 - Two for the Serial Synchronous Controller
 - Two for the Serial Peripheral Interface
 - One for the Analog-to-digital Converter
- · Low bus arbitration overhead
 - One Master Clock cycle needed for a transfer from memory to peripheral
 - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirements

Receive

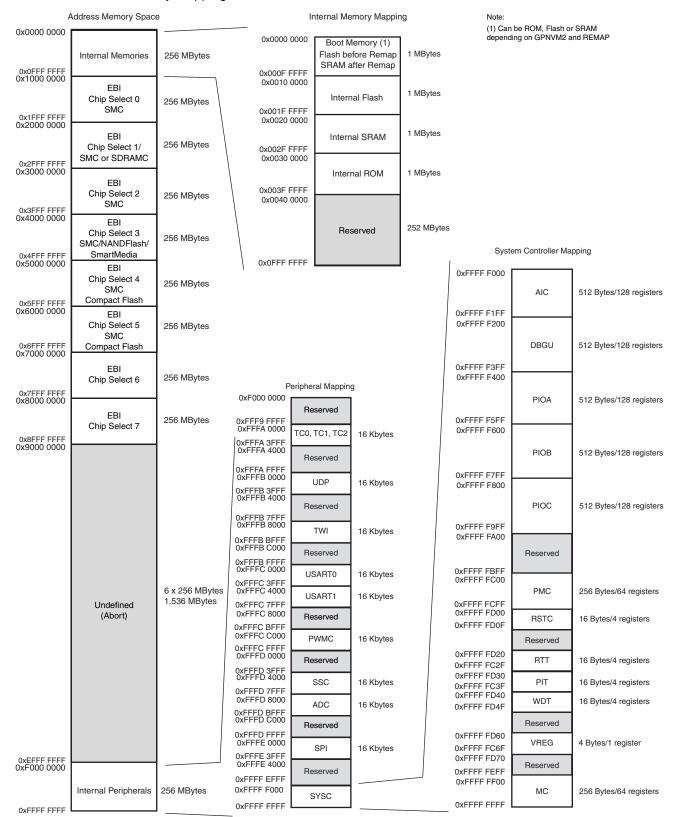
• Peripheral DMA Controller (PDC) priority is as follows (from the highest priority to the lowest):

DRGH

neceive	DBGU		
Receive	USART0		
Receive	USART1		
Receive	SSC		
Receive	ADC		
Receive	SPI		
Transmit	DBGU		
Transmit	USART0		
Transmit	USART1		
Transmit	SSC		
Transmit	SPI		



Figure 8-1. SAM7SE Memory Mapping



SAM7SE512/256/32 Summary

A first level of address decoding is performed by the Memory Controller, i.e., by the implementation of the Advanced System Bus (ASB) with additional features.

Decoding splits the 4G bytes of address space into 16 areas of 256M bytes. The areas 1 to 8 are directed to the EBI that associates these areas to the external chip selects NC0 to NCS7. The area 0 is reserved for the addressing of the internal memories, and a second level of decoding provides 1M byte of internal memory area. The area 15 is reserved for the peripherals and provides access to the Advanced Peripheral Bus (APB).

Other areas are unused and performing an access within them provides an abort to the master requesting such an access.

8.1 Embedded Memories

8.1.1 Internal Memories

8.1.1.1 Internal SRAM

The SAM7SE512/256 embeds a high-speed 32-Kbyte SRAM bank. The SAM7SE32 embeds a high-speed 8-Kbyte SRAM bank. After reset and until the Remap Command is performed, the SRAM is only accessible at address 0x0020 0000. After Remap, the SRAM also becomes available at address 0x0.

8.1.1.2 Internal ROM

The SAM7SE512/256/32 embeds an Internal ROM. At any time, the ROM is mapped at address 0x30 0000. The ROM contains the FFPI and the SAM-BA boot program.

8.1.1.3 Internal Flash

- The SAM7SE512 features two banks of 256 Kbytes of Flash.
- The SAM7SE256 features one bank of 256 Kbytes of Flash.
- The SAM7SE32 features one bank of 32 Kbytes of Flash.

At any time, the Flash is mapped to address 0x0010 0000.

A general purpose NVM (GPNVM) bit is used to boot either on the ROM (default) or from the Flash.

This GPNVM bit can be cleared or set respectively through the commands "Clear General-purpose NVM Bit" and "Set General-purpose NVM Bit" of the EFC User Interface.

Setting the GPNVM bit 2 selects the boot from the Flash, clearing it selects the boot from the ROM. Asserting ERASE clears the GPNVM bit 2 and thus selects the boot from the ROM by default.





The security bit can only be enabled through the Command "Set Security Bit" of the EFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1 and after a full flash erase is performed. When the security bit is deactivated, all accesses to the flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 200 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

8.1.2.5 Non-volatile Brownout Detector Control

Two general purpose NVM (GPNVM) bits are used for controlling the brownout detector (BOD), so that even after a power loss, the brownout detector operations remain in their state.

These two GPNVM bits can be cleared or set respectively through the commands "Clear General-purpose NVM Bit" and "Set General-purpose NVM Bit" of the EFC User Interface.

- GPNVM bit 0 is used as a brownout detector enable bit. Setting the GPNVM bit 0 enables the BOD, clearing it disables the BOD. Asserting ERASE clears the GPNVM bit 0 and thus disables the brownout detector by default.
- GPNVM bit 1 is used as a brownout reset enable signal for the reset controller. Setting the GPNVM bit 1 enables the brownout reset when a brownout is detected, Clearing the GPNVM bit 1 disables the brownout reset. Asserting ERASE disables the brownout reset by default.

8.1.2.6 Calibration Bits

Sixteen NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

8.1.3 Fast Flash Programming Interface

The Fast Flash Programming Interface allows programming the device through either a serial JTAG interface or through a multiplexed fully-handshaked parallel port. It allows gang-programming with market-standard industrial programmers.

The FFPI supports read, page program, page erase, full erase, lock, unlock and protect commands.

The Fast Flash Programming Interface is enabled and the Fast Programming Mode is entered when the TST pin and the PA0 and PA1 pins are all tied high and PA2 tied to low.

- The Flash of the SAM7SE512 is organized in 2048 pages of 256 bytes (dual plane). It reads as 131,072 32-bit words.
- The Flash of the SAM7SE256 is organized in 1024 pages of 256 bytes (single plane). It reads as 65,536 32-bit words.
- The Flash of the SAM7SE32 is organized in 256 pages of 128 bytes (single plane). It reads as 32,768 32-bit words.
- The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.
- The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

SAM7SE512/256/32 Summary

8.1.4 SAM-BA® Boot

The SAM-BA Boot is a default Boot Program which provides an easy way to program in-situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication via the DBGU or the USB Device Port.

- Communication via the DBGU supports a wide range of crystals from 3 to 20 MHz via software auto-detection.
- Communication via the USB Device Port is limited to an 18.432 MHz crystal.

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

The SAM-BA Boot is in ROM and is mapped in Flash at address 0x0 when GPNVM bit 2 is set to 0.

8.2 External Memories

The external memories are accessed through the External Bus Interface.

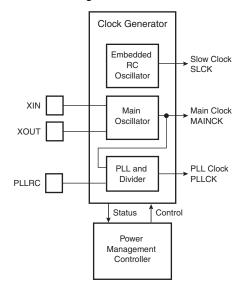
Refer to the memory map in Figure 8-1 on page 22.



- Main Oscillator frequency ranges between 3 and 20 MHz
- · Main Oscillator can be bypassed
- PLL output ranges between 80 and 220 MHz

It provides SLCK, MAINCK and PLLCK.

Figure 9-2. Clock Generator Block Diagram



9.3 Power Management Controller

The Power Management Controller uses the Clock Generator outputs to provide:

- the Processor Clock PCK
- the Master Clock MCK
- the USB Clock UDPCK
- all the peripheral clocks, independently controllable
- three programmable clock outputs

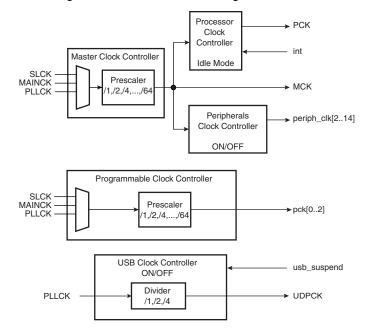
The Master Clock (MCK) is programmable from a few hundred Hz to the maximum operating frequency of the device.

The Processor Clock (PCK) switches off when entering processor idle mode, thus allowing reduced power consumption while waiting for an interrupt.





Figure 9-3. Power Management Controller Block Diagram



9.4 Advanced Interrupt Controller

- Controls the interrupt lines (nIRQ and nFIQ) of an ARM Processor
- · Individually maskable and vectored interrupt sources
 - Source 0 is reserved for the Fast Interrupt Input (FIQ)
 - Source 1 is reserved for system peripherals (RTT, PIT, EFC, PMC, DBGU, etc.)
 - Other sources control the peripheral interrupts or external interrupts
 - Programmable edge-triggered or level-sensitive internal sources
 - Programmable positive/negative edge-triggered or high/low level-sensitive external sources
- 8-level Priority Controller
 - Drives the normal interrupt nIRQ of the processor
 - Handles priority of the interrupt sources
 - Higher priority interrupts can be served during service of lower priority interrupt
- Vectoring
 - Optimizes interrupt service routine branch and execution
 - One 32-bit vector register per interrupt source
 - Interrupt vector register reads the corresponding current interrupt vector
- Protect Mode
 - Easy debugging by preventing automatic operations
- Fast Forcing
 - Permits redirecting any interrupt source on the fast interrupt
- General Interrupt Mask
 - Provides processor synchronization on events without triggering an interrupt



• Synchronous output, provides Set and Clear of several I/O lines in a single write

9.10 Voltage Regulator Controller

The purpose of this controller is to select the Power Mode of the Voltage Regulator between Normal Mode (bit 0 is cleared) or Standby Mode (bit 0 is set).



10.5 PIO Controller B Multiplexing

 Table 10-3.
 Multiplexing on PIO Controller B

PIO Controller B			Application U	Application Usage		
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments	
PB0	TIOA0	A0/NBS0				
PB1	TIOB0	A1/NBS2				
PB2	SCK0	A2				
PB3	NPCS3	A3				
PB4	TCLK0	A4				
PB5	NPCS3	A5				
PB6	PCK0	A6				
PB7	PWM3	A7				
PB8	ADTRG	A8				
PB9	NPCS1	A9				
PB10	NPCS2	A10				
PB11	PWM0	A11				
PB12	PWM1	A12				
PB13	PWM2	A13				
PB14	PWM3	A14				
PB15	TIOA1	A15				
PB16	TIOB1	A16/BA0				
PB17	PCK1	A17/BA1				
PB18	PCK2	D16				
PB19	FIQ	D17				
PB20	IRQ0	D18				
PB21	PCK1	D19				
PB22	NPCS3	D20				
PB23	PWM0	D21				
PB24	PWM1	D22				
PB25	PWM2	D23				
PB26	TIOA2	D24				
PB27	TIOB2	D25				
PB28	TCLK1	D26				
PB29	TCLK2	D27				
PB30	NPCS2	D28				
PB31	PCK2	D29				



10.13 USB Device Port

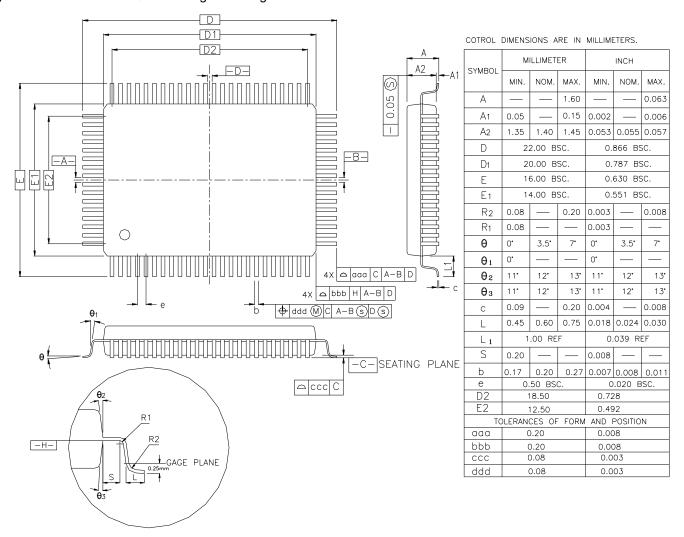
- USB V2.0 full-speed compliant,12 Mbits per second.
- Embedded USB V2.0 full-speed transceiver
- Embedded 2688-byte dual-port RAM for endpoints
- · Eight endpoints
 - Endpoint 0: 64bytes
 - Endpoint 1 and 2: 64 bytes ping-pong
 - Endpoint 3: 64 bytes
 - Endpoint 4 and 5: 512 bytes ping-pong
 - Endpoint 6 and 7: 64 bytes ping-pong
 - Ping-pong Mode (two memory banks) for Isochronous and bulk endpoints
- Suspend/resume logic
- Integrated Pull-up on DDP

10.14 Analog-to-Digital Converter

- 8-channel ADC
- 10-bit 384 Ksamples/sec. or 8-bit 583 Ksamples/sec. Successive Approximation Register ADC
- ±2 LSB Integral Non Linearity, ±1 LSB Differential Non Linearity
- Integrated 8-to-1 multiplexer, offering eight independent 3.3V analog inputs
- External voltage reference for better accuracy on low voltage inputs
- Individual enable and disable of each channel
- Multiple trigger sources
 - Hardware or software trigger
 - External trigger pin
 - Timer Counter 0 to 2 outputs TIOA0 to TIOA2 trigger
- Sleep Mode and conversion sequencer
 - Automatic wakeup on trigger and back to sleep mode after conversions of all enabled channels
- Each analog input shared with digital signals

11. Package Drawings

Figure 11-1. 128-lead LQFP Package Drawing







Revision History

Doc. Rev	Comments	Change Request Ref.
6222AS	First issue	
	Revised Memories with condensed mapping. Added Package Outlines and 144-ball LFBGA pin and ordering information.	#2709
6222BS	Section 12. "Ordering Information" on page 45 ordering information code reference changed	#3699
6222CS	Section 6.1 "JTAG Port Pins", Section 6.3 "Reset Pin", Section 6.5 "SDCK Pin", removed statement: "not 5V tolerant" Section 7.6 "SDRAM Controller", Mobile SDRAM controller added to SDRAMC features INL and DNL updated in Section 10.14 "Analog-to-Digital Converter" "Features" on page 2, Fully Static Operation; added, up to 55 MHz at 1.8V and 85°C worst case conditions Section 7.1 "ARM7TDMI Processor", Runs at up to 55 MHz, providing 0.9 MIPS/MHz (core supplied with 1.8V) Section 7.8 "Peripheral DMA Controller" PDC priority list added Section 7.5 "Static Memory Controller", Multiple device adaptability includes: compliant w/PSRAM in synchronous operations.	#3826 #4005 #3924 #3833 review
6222DS	Figure 8-1 "SAM7SE Memory Mapping" Compact Flash not shown w/EBI Chip Select 5. Compact Flash is shown with EBI Chip Select 2. Section 8.1.2.1 "Flash Overview", updated AT91SAM7SE32 "reads as 8192 32-bit words." Section 6. "/O Lines Considerations", "JTAG Port Pins", "Test Pin", "Reset Pin", "ERASE Pin" descriptions updated	4804 4512 5062
6222ES	Section 10.11 "Timer Counter",the TC has two output compare and one input capture per channel.	4209
6222FS	Features: "Mode for General Purpose Two-wire UART Serial Communication" added to "Debug Unit (DBGU)". Signal Description: Table 3-1, "Signal Description List", AD0-AD3 and AD4-AD7 comments reversed. System Controller:	5846 5271
	Figure 9-1 "System Controller Block Diagram", 'periph_nreset' changed into 'power_on_reset' for RTT.	5222
6222GS	MRL B Ordering Codes added to Table 12-1, "Ordering Information" 'Product Description' changed to 'AT91SAM ARM-based Flash MCU' on the first page. 'AT91SAM' product prefix changed to 'SAM', except for Chip ID and ordering codes.	7749 rfo